

Philips Components

Data sheet	
status	Preliminary specification
date of issue	March 1991

PHILIPS INTERNATIONAL

56E D ■ 7110826 0044548 563 ■ PHIN

GENERAL DESCRIPTION

N-channel enhancement mode field-effect power transistor in a plastic full-pack envelope.
The device is intended for use in Switched Mode Power Supplies (SMPS), motor control, welding, DC/DC and AC/DC converters, and in general purpose switching applications.

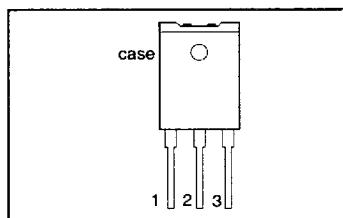
PINNING - SOT199

PIN	DESCRIPTION
1	gate
2	drain
3	source
case	isolated

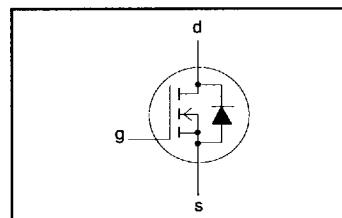
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
V_{DS}	BUK428	-1000A	-1000B	
I_D	Drain-source voltage	1000	1000	V
P_{tot}	Drain current (DC)	2.9	2.6	A
$R_{DS(ON)}$	Total power dissipation	45	45	W
	Drain-source on-state resistance	2.0	2.6	Ω

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{DS} V_{DGR} $\pm V_{GS}$	Drain-source voltage	$R_{GS} = 20 \text{ k}\Omega$	-	1000	V
	Drain-gate voltage		-	1000	V
	Gate-source voltage		-	30	V
I_D I_D^P I_{DM}	Drain current (DC)	$T_{hs} = 25^\circ\text{C}$ $T_{hs} = 100^\circ\text{C}$ $T_{hs} = 25^\circ\text{C}$	-	-1000A	A
	Drain current (DC)		-	2.9	A
	Drain current (pulse peak value)		-	1.9	A
P_{tot} T_{stg} T_J	Total power dissipation	$T_{hs} = 25^\circ\text{C}$	-	45	W
	Storage temperature		-55	150	$^\circ\text{C}$
	Junction Temperature		-	150	$^\circ\text{C}$

PowerMOS transistor**BUK428-1000A/B**

PHILIPS INTERNATIONAL

56E D ■ 7110826 0044549 4TT ■ PHIN

THERMAL RESISTANCES

From junction to heatsink	with heatsink compound	$R_{th\,J-hs} = 2.8 \text{ K/W}$
From junction to ambient	-	$R_{th\,J-a} = 35 \text{ K/W}$

STATIC CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 0.25 \text{ mA}$	1000	-	-	V
$V_{GS(TO)}$	Gate threshold voltage	$V_{DS} = V_{GS}; I_D = 1 \text{ mA}$	2.1	3.0	4.0	V
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 1000 \text{ V}; V_{GS} = 0 \text{ V}; T_J = 25^\circ\text{C}$	-	5	50	μA
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 1000 \text{ V}; V_{GS} = 0 \text{ V}; T_J = 125^\circ\text{C}$	-	0.1	1.0	mA
I_{GSS}	Gate source leakage current	$V_{GS} = \pm 30 \text{ V}; V_{DS} = 0 \text{ V}$	-	10	100	nA
$R_{DS(ON)}$	Drain-source on-state resistance	$V_{GS} = 10 \text{ V}; I_D = 3.5 \text{ A}$ BUK428-1000A $V_{GS} = 10 \text{ V}; I_D = 3.5 \text{ A}$ BUK428-1000B	-	1.8	2.0	Ω
			-	2.2	2.6	Ω

DYNAMIC CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
g_{fs}	Forward transconductance	$V_{DS} = 25 \text{ V}; I_D = 3.5 \text{ A}$	2.5	5.0	-	S
C_{iss}	Input capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz}$	-	3000	3500	pF
C_{oss}	Output capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz}$	-	300	350	pF
C_{rss}	Feedback capacitance	$V_{GS} = 0 \text{ V}; V_{DS} = 25 \text{ V}; f = 1 \text{ MHz}$	-	150	250	pF
$t_{d\,on}$	Turn-on delay time	$V_{DD} = 30 \text{ V}; I_D = 2.5 \text{ A}; V_{GS} = 10 \text{ V}; R_{GS} = 50 \Omega; R_{gen} = 50 \Omega$	-	60	90	ns
t_r	Turn-on rise time	$V_{DD} = 30 \text{ V}; I_D = 2.5 \text{ A}; V_{GS} = 10 \text{ V}; R_{GS} = 50 \Omega; R_{gen} = 50 \Omega$	-	100	140	ns
$t_{d\,off}$	Turn-off delay time	$V_{DD} = 30 \text{ V}; I_D = 2.5 \text{ A}; V_{GS} = 10 \text{ V}; R_{GS} = 50 \Omega; R_{gen} = 50 \Omega$	-	350	430	ns
t_f	Turn-off fall time	$V_{DD} = 30 \text{ V}; I_D = 2.5 \text{ A}; V_{GS} = 10 \text{ V}; R_{GS} = 50 \Omega; R_{gen} = 50 \Omega$	-	100	140	ns
L_d	Internal drain inductance	Measured from drain lead 6 mm from package to centre of die	-	5	-	nH
L_s	Internal source inductance	Measured from source lead 6 mm from package to source bond pad	-	12.5	-	nH

ISOLATION $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{isol}	Repetitive peak voltage from all three terminals to external heatsink	R.H. $\leq 65\%$; clean and dustfree	-	-	2500	V
C_{isol}	Capacitance from T2 to external heatsink	$f = 1 \text{ MHz}$	-	22	-	pF

PowerMOS transistor**BUK428-1000A/B**

PHILIPS INTERNATIONAL

56E D ■ 7110826 0044550 111 ■ PHIN

REVERSE DIODE LIMITING VALUES AND CHARACTERISTICS $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_{DR}	Continuous reverse drain current	-	-	-	2.9	A
I_{DRM}	Pulsed reverse drain current	-	-	-	12	A
V_{SD}	Diode forward voltage	$I_F = 2.9 \text{ A}; V_{GS} = 0 \text{ V}$	-	0.9	1.3	V
t_{rr}	Reverse recovery time	$I_F = 2.9 \text{ A}; -dI_F/dt = 100 \text{ A}/\mu\text{s}$	-	1.5	-	μs
	Reverse recovery charge	$V_{GS} = 0 \text{ V}; V_R = 100 \text{ V}$	-	20	-	μC

AVALANCHE LIMITING VALUE $T_{hs} = 25^\circ\text{C}$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
W_{DSS}	Drain-source non-repetitive unclamped inductive turn-off energy	$I_D = 6.5 \text{ A}; V_{DD} \leq 250 \text{ V}; V_{GS} = 10 \text{ V}; R_{GS} = 50 \Omega$	-	-	750	mJ